



Abstract

A solid electrolytic capacitor having excellent solder wettability and heat resisting adhesion and a method of manufacturing same are obtained by a simple plating configuration. The capacitor includes a capacitor element, positive electrode terminal and negative electrode terminal. The positive electrode terminal and the negative electrode terminal include a metallic member containing (i) at least one selected from the group consisting of nickel, nickel alloy, copper and copper alloy, (ii) a first plated layer of tin or tin alloy, directly disposed without undercoat on the metallic member, and (iii) an intermetallic compound layer formed between the metallic member and the first plated layer. The intermetallic compound layer contains tin-nickel or tin-copper formed through heat reflow treatment of the metallic member disposed on the first plated layer.

Figure 1